

Features

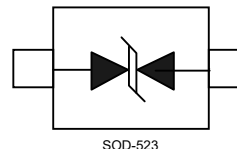
100Watts peak pulse power ($t_p = 8/20\mu s$)
 Bidirectional configurations
 Solid-state silicon-avalanche technology
 Low clamping voltage
 Low leakage current
 IEC 61000-4-2 $\pm 16kV$ contact $\pm 16kV$ air
 IEC 61000-4-4 (EFT) 40A (5/50ns)
 IEC 61000-4-5 (Lightning) 9A (8/20 μs)

Mechanical Data

SOD523 package
 Molding compound flammability rating: UL 94V-0
 Packaging: Tape and Reel
 RoHS/WEEE Compliant

Applications

Microprocessor based equipment
 Personal Digital Assistants (PDA's)
 Notebooks, Desktops, and Servers
 Portable Instrumentation
 Pagers Peripherals



Absolute Maximum Rating

Rating	Symbol	Value	Units
Peak Pulse Power ($t_p = 8/20\mu s$)	P_{PP}	100	Watts
Peak Pulse Current ($t_p = 8/20\mu s$) (note1)	I_{pp}	9	A
ESD per IEC 61000-4-2 (Air) ESD per IEC 61000-4-2 (Contact)	V_{ESD}	25 25	kV
Lead Soldering Temperature	T_L	260(10seconds)	$^{\circ}C$
Junction Temperature	T_J	-55 to + 125	$^{\circ}C$
Storage Temperature	T_{stg}	-55 to + 150	$^{\circ}C$

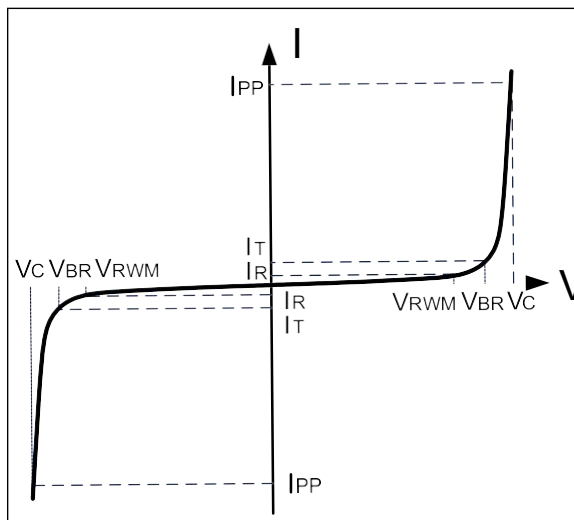
Electrical Characteristics

Parameter	Symbol	Conditions	Min	Typical	Max	Units
Reverse Stand-Off Voltage	V_{RWM}				5.0	V
Reverse Breakdown Voltage	V_{BR}	$I_T=1mA$	5.6			V
Reverse Leakage Current	I_R	$V_{RWM}=5.0V, T=25^{\circ}C$			1	μA
Clamping Voltage	V_C	$I_{PP}=9A, t_p=8/20\mu s$			11	V
Junction Capacitance	C_j	$V_R = 0V, f = 1MHz$		17		pF

Electrical Parameters (TA = 25°C unless otherwise noted)

Symbol	Parameter
I_{PP}	Maximum Reverse Peak Pulse Current
V_C	Clamping Voltage @ I_{PP}
V_{RWM}	Working Peak Reverse Voltage
I_R	Maximum Reverse Leakage Current @ V_{RWM}
V_{BR}	Breakdown Voltage @ I_T
I_T	Test Current

Note: 8/20 μs pulse waveform.



RATING AND CHARACTERISTIC CURVES

Figure 1: Peak Pulse Power vs. Pulse Time

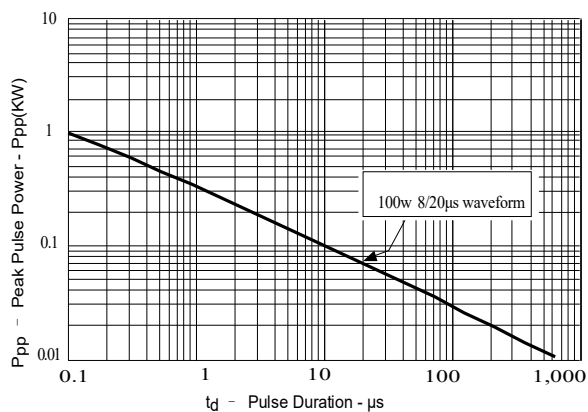


Figure 2: Power Derating Curve

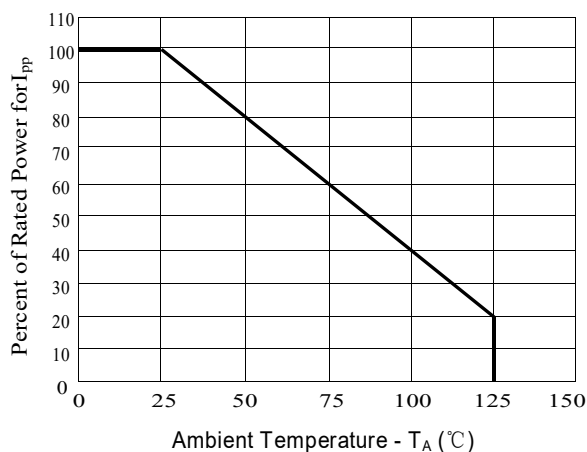


Figure3: Pulse Waveform

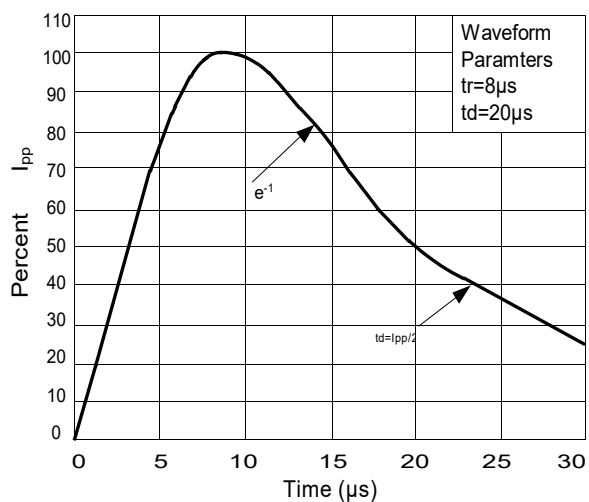
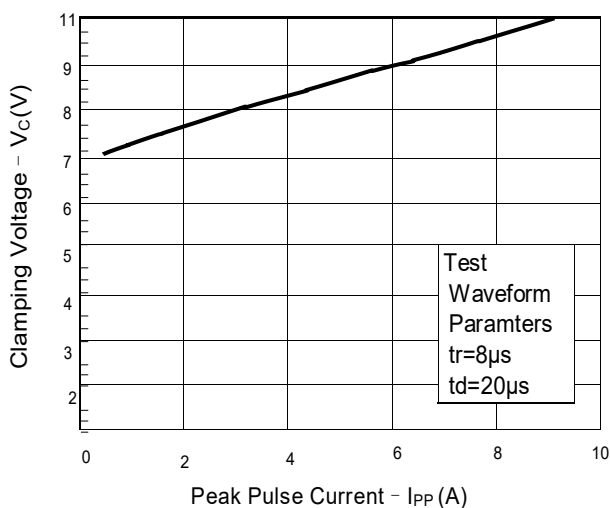
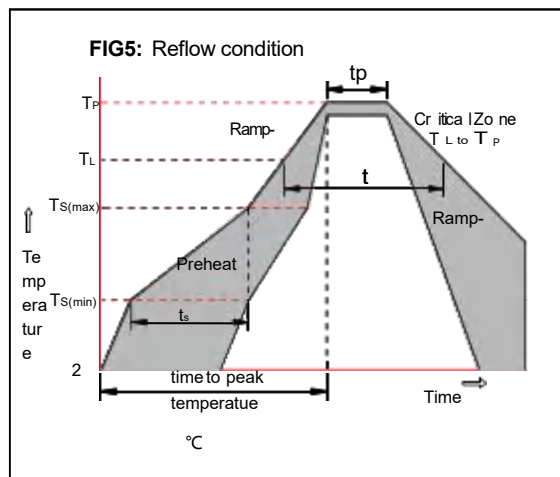


Figure 4: Clamping Voltage vs. Ipp



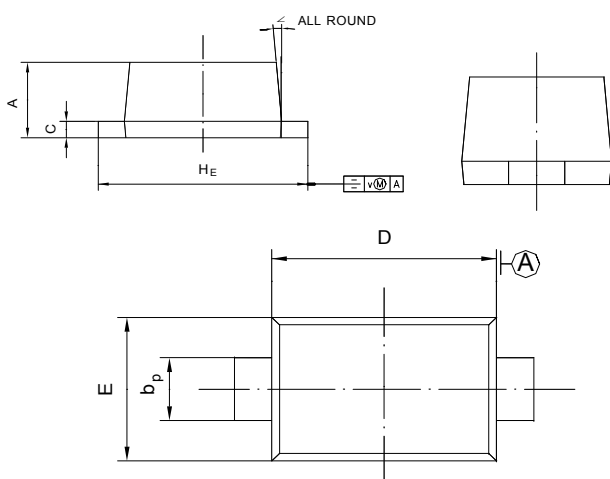
Soldering parameters

Reflow Condition		Pb-Free assembly (see as below)
Pre Heat	-Temperature Min ($T_{s(min)}$)	+150 °C
	-Temperature Max($T_{s(max)}$)	+200 °C
	-Time (Min to Max) (ts)	60-180 secs.
Average ramp up rate (Liquid us Temp (T_L) to peak)		3 °C/sec. Max
$T_{s(max)}$ to T_L - Ramp-up Rate		3 °C/sec. Max
Reflow	-Temperature(T_L)(Liquid us)	+217 °C
	-Temperature(t_L)	60-150 secs.
Peak Temp (T_P)		+260(+0/-5) °C
Time within 5 °C of actual Peak Temp (t_p)		30 secs. Max
Ramp-down Rate		6 °C/sec. Max
Time 25 °C to Peak Temp (T_P)		8 min. Max
Do not exceed		+260 °C

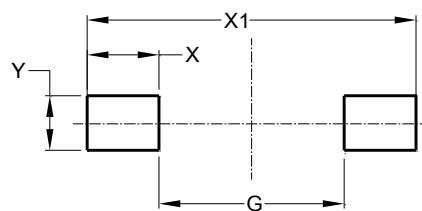


Package Dimensions & Suggested Pad Layout

SOD523

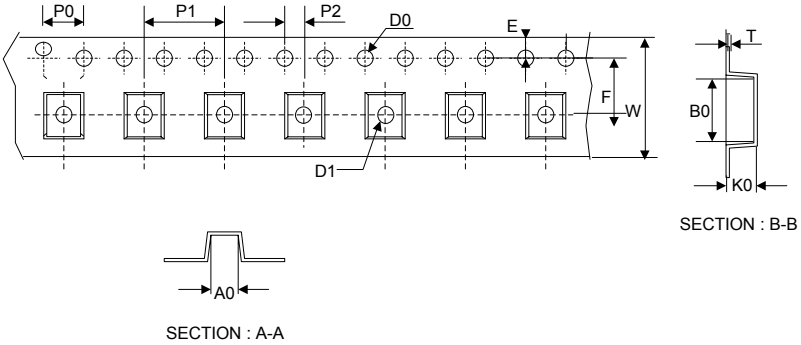
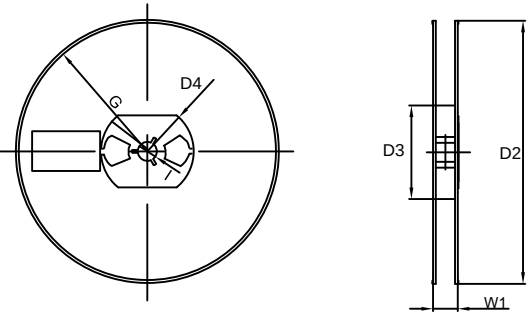


UNIT	A	b _p	C	D	E	H _E	V	∠
mm	0.70 0.50	0.40 0.20	0.14 0.05	1.30 1.10	0.90 0.75	1.70 1.50	0.1	5°



Dimensions	Value (in mm)
G	0.85
X	0.70
X1	2.25
Y	0.80

Tape & reel specification

Tape		Symbol	Dimension (mm)
		P0	4.00±0.20
		P1	2.00±0.20
		P2	2.00±0.20
		D0	1.55±0.20
		D1	0.50±0.20
		E	1.55±0.25
		F	3.60±0.20
		W	8.00±0.20
		A0	1.30±0.20
		B0	2.35±0.20
		K0	0.95±0.20
		T	0.20±0.20
		D2	177.0±5.0
		D3	55Min.
		D4	R24.6±2.0
7" Reel		G	R82.0±2.0
		I	13.0±2.0
		W1	10.20±3.0
		Quantity: 3000PCS	